



## Material Content Data Sheet



<b>Sales Product Name</b>		IPA030N10N3 G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000800284						
<b>Package</b>		PG-TO220-3-111		<b>Weight*</b>		2233.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.455	0.69	0.69	6920	6920
leadframe	non noble metal	iron	7439-89-6	1.120	0.05		501	
	inorganic material	phosphorus	7723-14-0	0.336	0.02		150	
	non noble metal	copper	7440-50-8	1118.332	50.07	50.14	500748	501399
wire	non noble metal	aluminium	7429-90-5	9.385	0.42	0.42	4202	4202
encapsulation	organic material	carbon black	1333-86-4	2.237	0.10		1002	
	plastics	epoxy resin	-	203.091	9.09		90937	
	inorganic material	silicondioxide	60676-86-0	870.037	38.96	48.15	389571	481510
leadfinish	non noble metal	tin	7440-31-5	7.942	0.36	0.36	3556	3556
plating	non noble metal	nickel	7440-02-0	0.305	0.01		137	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	137
solder	non noble metal	antimony	7440-36-0	0.508	0.02		228	
	noble metal	silver	7440-22-4	1.271	0.06		569	
	non noble metal	tin	7440-31-5	3.304	0.15	0.23	1479	2276
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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